

**SINGLE CHANNEL:
DUAL CHANNEL:**

**FOD070L
FOD073L**

FOD270L

DESCRIPTION

The FOD070L, FOD270L and FOD073L optocouplers consist of an AlGaAs LED optically coupled to a high gain split darlington photodetector. These devices are specified to operate at a 3.3V supply voltage.

The split darlington configuration separating the input photodiode and the first stage gain from the output transistor permits lower output saturation voltage and higher speed operation than possible with conventional darlington phototransistor optocoupler. In the dual channel device FOD073L, an integrated emitter – base resistor provides superior stability over temperature.

The combination of a very low input current of 0.5 mA and a high current transfer ratio of 2000% makes this family particularly useful for input interface to MOS, CMOS, LSTTL and EIA RS232C, while output compatibility is ensured to LVCMOS as well as high fan-out LVTTTL requirements.

An internal noise shield provides exceptional common mode rejection of 10 kV/μs.

FEATURES

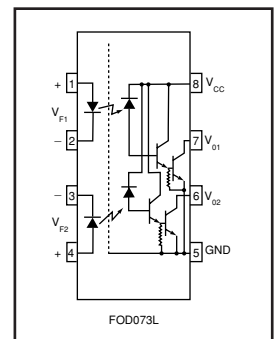
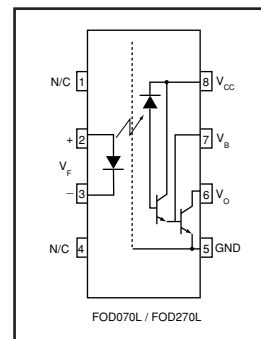
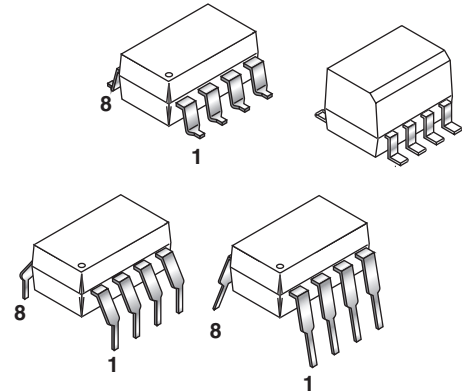
- Low power consumption
- Low input current - 0.5 mA
- Available in single channel 8-pin DIP (FOD270L), 8-pin SOIC (FOD070L) and dual channel 8-pin SOIC
- High CTR-2000%
- High CMR-10 kV/μs
- Guaranteed performance over temperature 0°C to 70°C
- U.L. recognized (File # E90700)
- LVTTTL/LVCMOS Compatible output

APPLICATIONS

- Digital logic ground isolation – LVTTTL/LVCMOS
- Telephone ring detector
- EIA-RS-232C line receiver
- High common mode noise line receiver
- μP bus isolation
- Current loop receiver

TRUTH TABLE

LED	V _O
ON	LOW
OFF	HIGH



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ABSOLUTE MAXIMUM RATINGS (No derating required up to 85°C)

Parameter	Symbol	Value	Units
Storage Temperature	T_{STG}	-40 to +125	°C
Operating Temperature	T_{OPR}	-40 to +85	°C
Lead Solder Temperature (Wave solder only. See reflow profile for surface mount devices)	T_{SOL}	260 for 10 sec	°C
EMITTER			
DC/Average Forward Input Current	I_F (avg)	20	mA
Peak Forward Input Current (50% duty cycle, 1 ms P.W.)	I_F (pk)	40	mA
Peak Transient Input Current - ($\leq 1 \mu s$ P.W., 300 pps)	I_F (trans)	1.0	A
Reverse Input Voltage	V_R	5	V
Input Power Dissipation	P_D	35	mW
DETECTOR			
Average Output Current	I_O (avg)	60	mA
Emitter-Base Reverse Voltage (FOD070L, FOD270L)	V_{EB}	0.5	V
Supply Voltage, Output Voltage	V_{CC}, V_O	-0.5 to 7	V
Output power dissipation	P_D	100	mW

ELECTRICAL CHARACTERISTICS ($T_A = 0$ to 70°C Unless otherwise specified)

INDIVIDUAL COMPONENT CHARACTERISTICS

Parameter	Test Conditions	Symbol	Device	Min	Typ**	Max	Unit
EMITTER							
Input Forward Voltage	$T_A = 25^\circ C$	V_F	All		1.35	1.7	V
	Each Channel ($I_F = 1.6$ mA)					1.75	
Input Reverse Breakdown Voltage	($T_A = 25^\circ C, I_R = 10 \mu A$) Each Channel	BV_R	All	5.0			V
DETECTOR							
Logic high output current	($I_F = 0$ mA, $V_O = V_{CC} = 3.3$ V)	I_{OH}	FOD070L FOD270L		0.05	25	μA
	Each Channel		FOD073L				
Logic Low Supply Current	$I_F = 1.6$ mA, $V_O = \text{Open}$, $V_{CC} = 3.3$ V	I_{CCL}	FOD070L FOD270L		0.5	1.5	mA
	$I_{F1} = I_{F2} = 1.6$ mA $V_{O1} = V_{O2} = \text{Open}$, $V_{CC} = 3.3$ V		FOD073L		0.8	3	
Logic High Supply Current	$I_F = 0$ mA, $V_O = \text{Open}$, $V_{CC} = 3.3$ V	I_{CCH}	FOD070L FOD270L		0.01	1	μA
	$I_{F1} = I_{F2} = 0$ mA $V_{O1} = V_{O2} = \text{Open}$, $V_{CC} = 3.3$ V		FOD073L		0.01	2	

** All typicals at $T_A = 25^\circ C$

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TRANSFER CHARACTERISTICS ($T_A = 0$ to 70°C Unless otherwise specified)

Parameter	Test Conditions	Symbol	Device	Min	Typ**	Max	Unit
COUPLED							
Current transfer ratio (Notes 1,2)	($I_F = 0.5\text{ mA}$, $V_O = 0.4\text{ V}$, $V_{CC} = 3.3\text{ V}$)	CTR	ALL	400		7000	%
Logic low output voltage output voltage (Note 2)	($I_F = 1.6\text{ mA}$, $I_O = 8\text{ mA}$, $V_{CC} = 3.3\text{ V}$)	V_{OL}	ALL		0.07	0.3	V
	($I_F = 5\text{ mA}$, $I_O = 15\text{ mA}$, $V_{CC} = 3.3\text{ V}$)		ALL		0.07	0.4	

** All typicals at $T_A = 25^\circ\text{C}$

SWITCHING CHARACTERISTICS ($T_A = 0$ to 70°C unless otherwise specified., $V_{CC} = 3.3\text{ V}$)

Parameter	Test Conditions	Symbol	Device	Min	Typ**	Max	Unit
Propagation delay time to logic low	(R _L = 4.7 kΩ, I _F = 0.5 mA) (Note 2) (Fig. 17)	T _{PHL}	FOD070L		3	30	μs
			FOD270L				
			FOD073L		5		
Propagation delay time to logic high	(R _L = 4.7 kΩ, I _F = 0.5 mA) (Note 2) (Fig. 17)	T _{PLH}	FOD070L		50	90	μs
			FOD270L				
			FOD073L		25		
Common mode transient immunity at logic high	(I _F = 0 mA, V _{CM} = 10 V _{P-P}) T _A = 25°C (R _L = 2.2 kΩ) (Note 3) (Fig. 18)	CM _H	ALL	1,000	10,000		V/μs
Common mode transient immunity at logic low	(I _F = 1.6 mA, V _{CM} = 10 V _{P-P} , R _L = 2.2 kΩ) T _A = 25°C (Note 3) (Fig. 18)	CM _L	ALL	1,000	10,000		V/μs

** All typicals at $T_A = 25^\circ\text{C}$

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ISOLATION CHARACTERISTICS ($T_A = 0$ to 70°C Unless otherwise specified)

Characteristics	Test Conditions	Symbol	Device	Min	Typ**	Max	Unit
Input-output insulation leakage current	(Relative humidity = 45%) ($T_A = 25^\circ\text{C}$, $t = 5$ s) ($V_{I-O} = 3000$ VDC) (Note 4)	I_{I-O}	ALL			1.0	μA
Withstand insulation test voltage	(RH $\leq 50\%$, $T_A = 25^\circ\text{C}$) (Note 4) ($t = 1$ min.)	V_{ISO}	FOD070L FOD073L	2500			V_{RMS}
			FOD270L	5000			
Resistance (input to output)	(Note 4) ($V_{I-O} = 500$ VDC)	R_{I-O}	ALL		10^{12}		Ω
Capacitance (input to output)	(Note 4,5) ($f = 1$ MHz)	C_{I-O}	ALL		0.7		pF
Input-Input Insulation leakage current	(RH $\leq 45\%$, $V_{I-I} = 500$ VDC (Note 6))	I_{I-I}	FOD073L	0.005			μA
Input-Input Resistance	($V_{I-I} = 500$ VDC) (Note 6)	R_{I-I}	FOD073L		10^{11}		Ω
Input-Input Capacitance	($f = 1$ MHz) (Note 6)	C_{I-I}	FOD073L		0.03		pF

** All typicals at $T_A = 25^\circ\text{C}$

NOTES

1. Current Transfer Ratio is defined as a ratio of output collector current, I_O , to the forward LED input current, I_F times 100%.
2. Pin 7 open. (FOD070L and FOD270L only)
3. Common mode transient immunity in logic high level is the maximum tolerable (positive) dV_{CM}/dt on the leading edge of the common mode pulse signal, V_{CM} , to assure that the output will remain in a logic high state (i.e., $V_O > 2.0$ V). Common mode transient immunity in logic low level is the maximum tolerable (negative) dV_{CM}/dt on the trailing edge of the common mode pulse signal, V_{CM} , to assure that the output will remain in a logic low state (i.e., $V_O < 0.8$ V).
4. Device is considered a two terminal device: Pins 1, 2, 3 and 4 are shorted together and Pins 5, 6, 7 and 8 are shorted together.
5. For dual channel devices, C_{I-O} is measured by shorting pins 1 and 2 or pins 3 and 4 together and pins 5 through 8 shorted together.
6. Measured between pins 1 and 2 shorted together, and pins 3 and 4 shorted together.

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TYPICAL PERFORMANCE CURVES

Fig. 1 Input Forward Current vs Forward Voltage

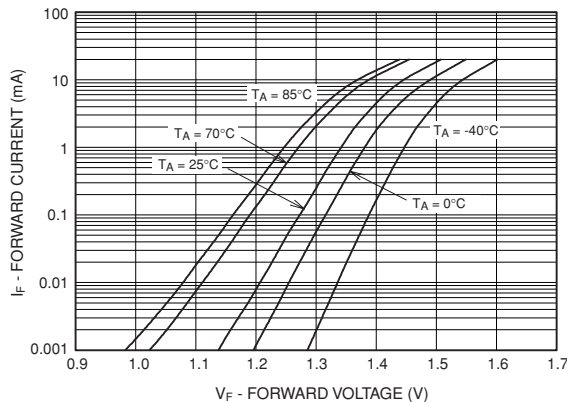


Fig. 2 Current Transfer Ratio vs. Input Forward Current (FOD270L only)

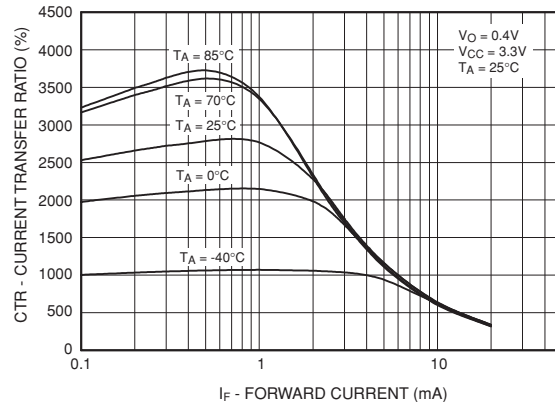


Fig. 3 Current Transfer Ratio vs. Input Forward Current (FOD070L only)

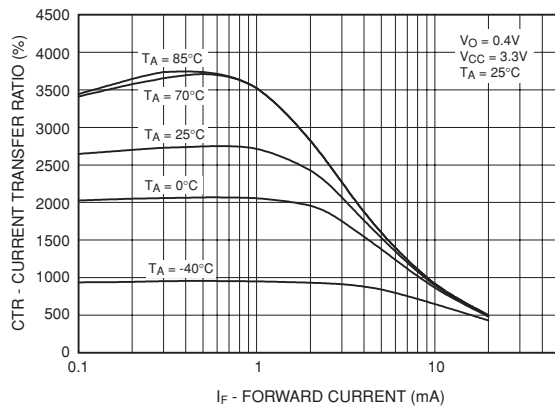


Fig. 4 Current Transfer Ratio vs. Input Forward Current (FOD073L only)

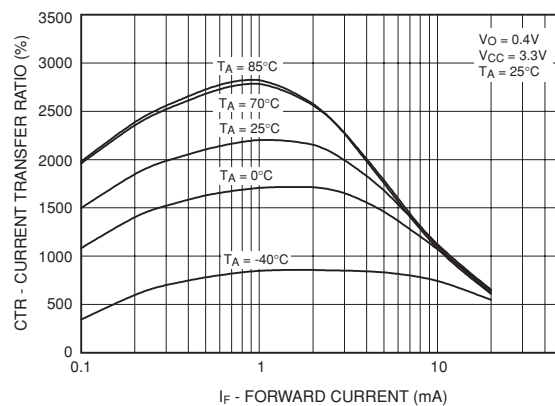


Fig. 5 DC Transfer Characteristics (FOD070L, FOD270L)

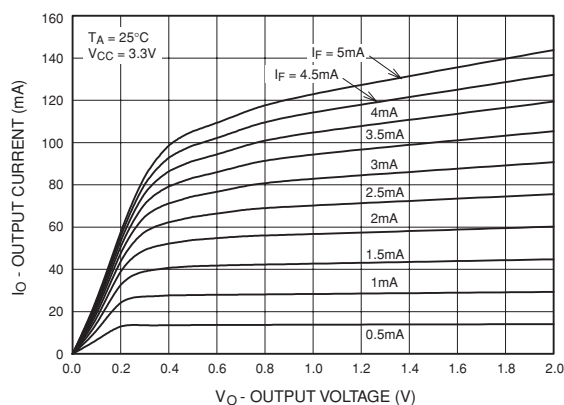
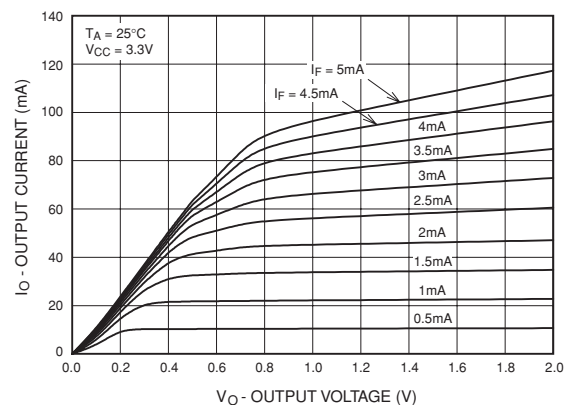


Fig. 6 DC Transfer Characteristics (FOD073L only)



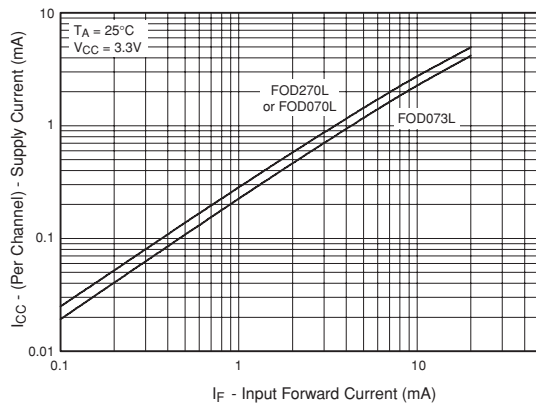
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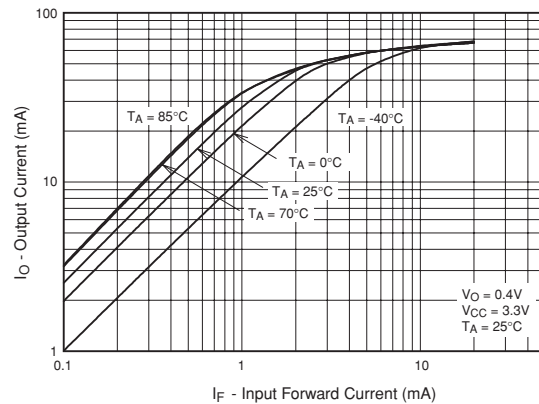
FOD270L

TYPICAL PERFORMANCE CURVES

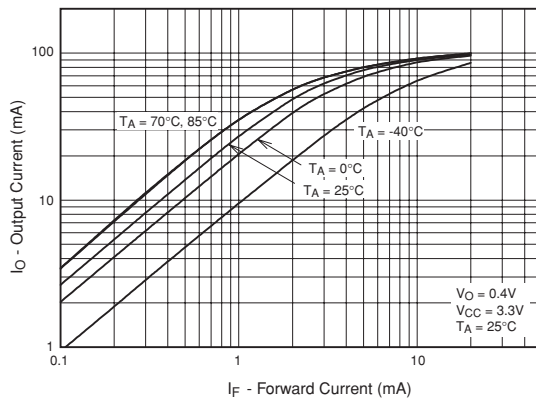
**Fig. 7 Supply Current vs Input Forward Current
(FOD270L, FOD070L, FOD073L)**



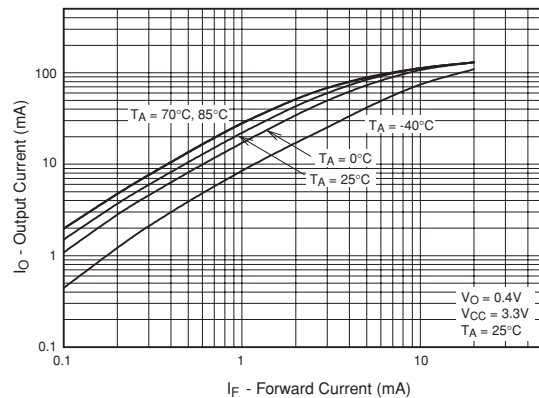
**Fig. 8 Output Current vs Input Forward Current
(FOD270L only)**



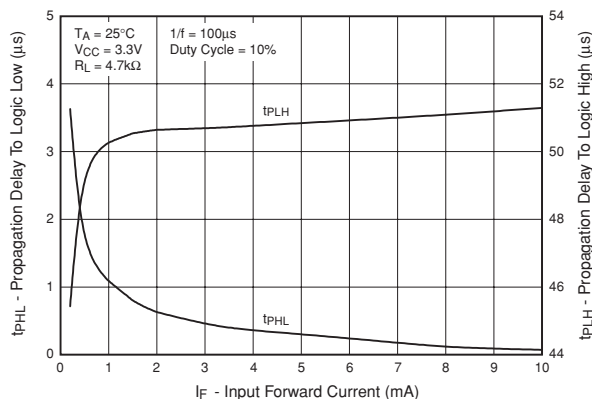
**Fig. 9 Output Current vs Input Forward Current
(FOD070L only)**



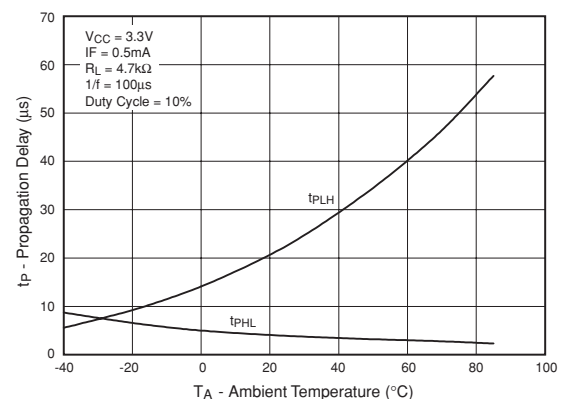
**Fig. 10 Output Current vs Input Forward Current
(FOD073L only)**



**Fig. 11 Propagation Delay vs.
Input Forward Current (FOD070L only)**



**Fig. 12 Propagation Delay vs.
Ambient Temperature (FOD073L only)**



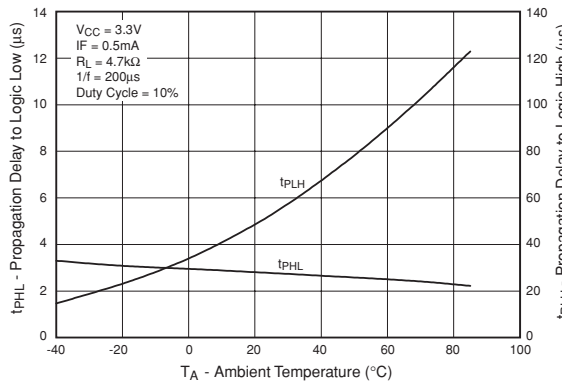
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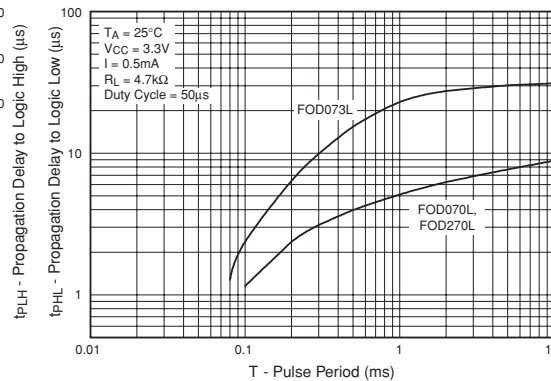
FOD270L

TYPICAL PERFORMANCE CURVES

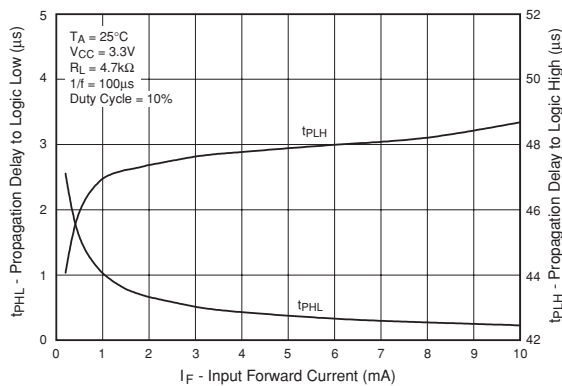
**Fig. 13 Propagation Delay vs.
Ambient Temperature (FOD070L, FOD270L)**



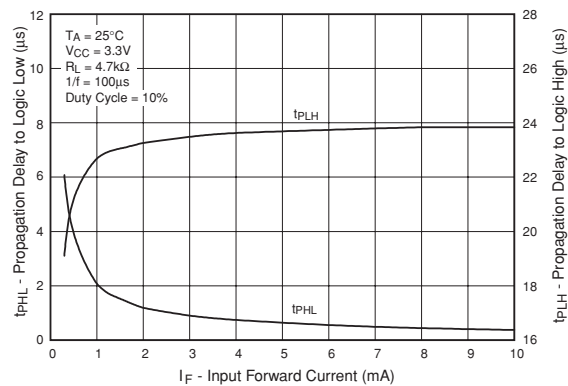
**Fig. 14 Propagation Delay To Logic Low vs Pulse Period
(FOD073L, FOD070L, FOD270L)**



**Fig. 15 Propagation Delay vs.
Input Forward Current (FOD270L only)**



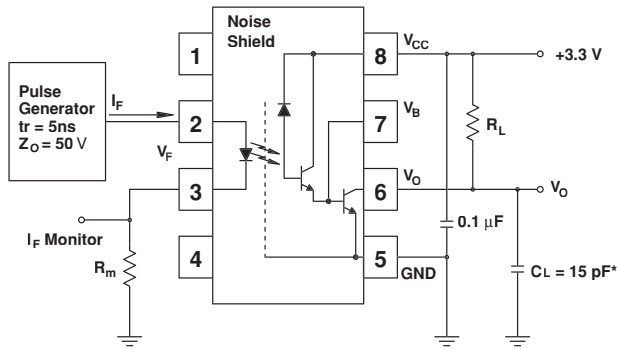
**Fig. 16 Propagation Delay vs.
Input Forward Current (FOD073L only)**



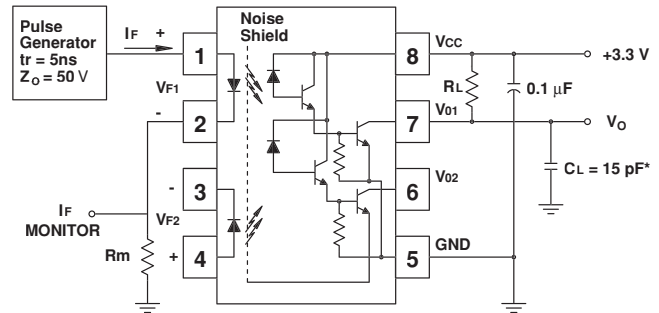
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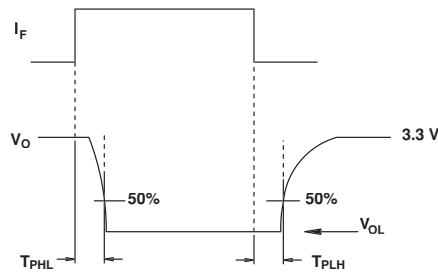
FOD270L



Test Circuit for FOD070L, FOD270L



Test Circuit for FOD073L



*Includes Probe and Fixture Capacitance

Fig. 17 Switching Time Test Circuit

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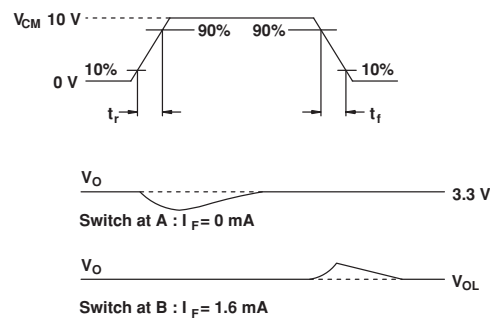
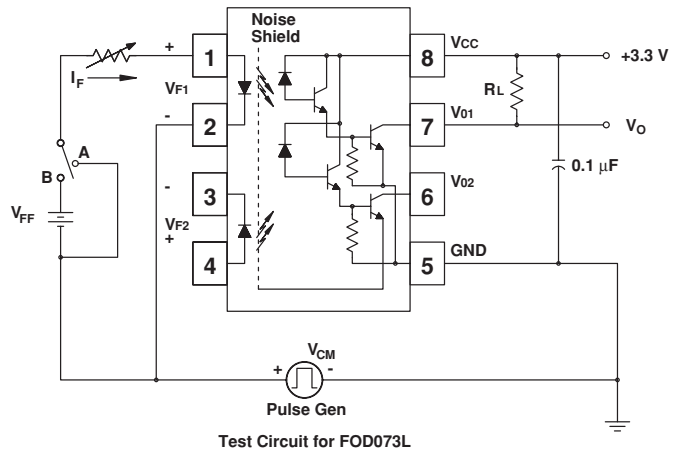
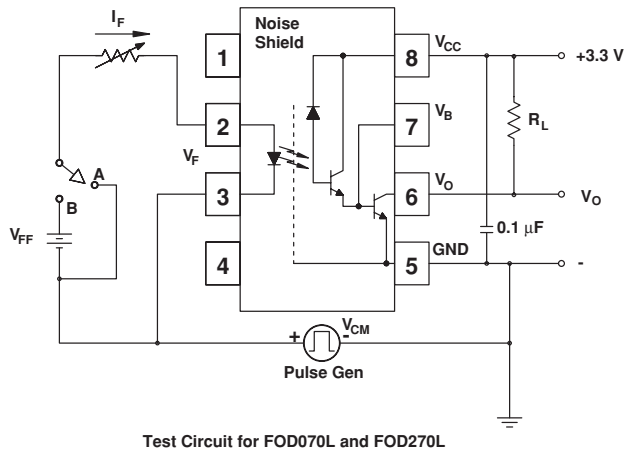


Fig. 18 Common Mode Immunity Test Circuit

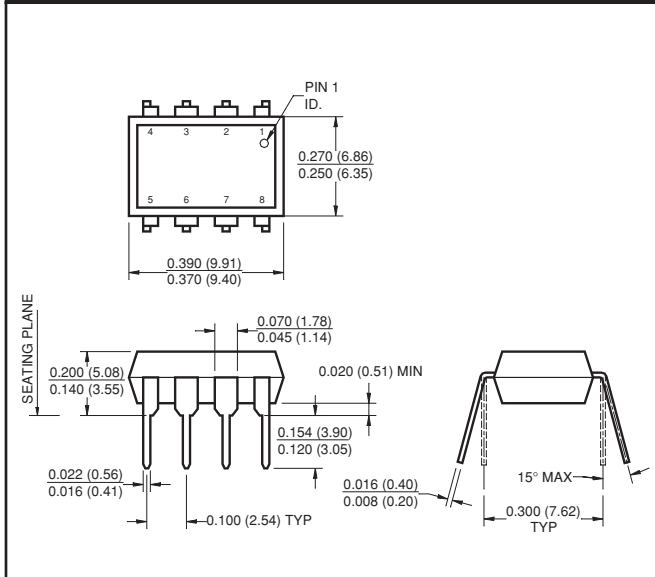
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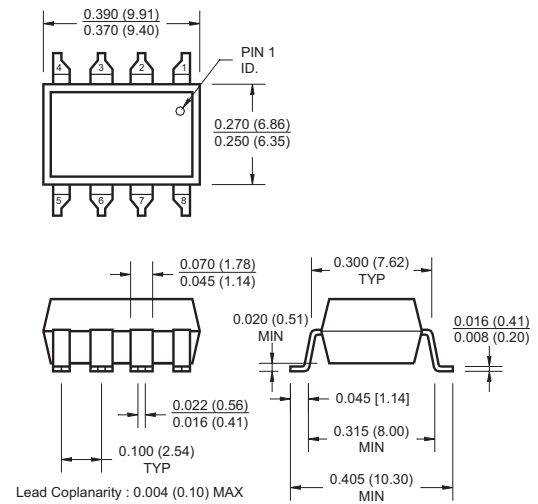
FOD270L

8-Pin DIP

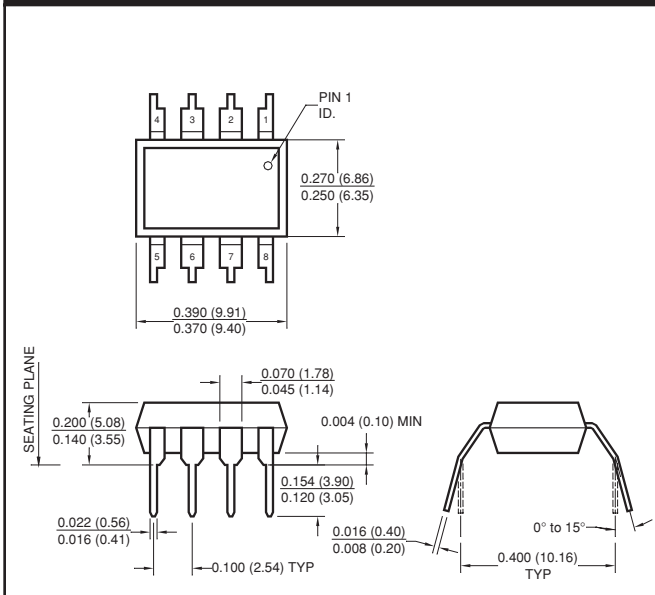
Package Dimensions (Through Hole)



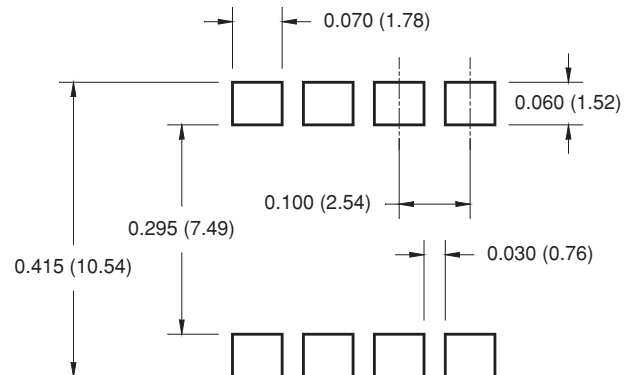
Package Dimensions (Surface Mount)



Package Dimensions (0.4"Lead Spacing)



**Recommend Pad Layout for
Surface Mount Leadform**



NOTE

All dimensions are in inches (millimeters)

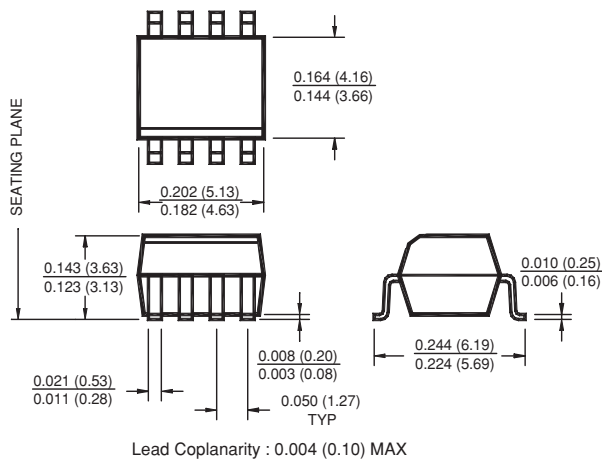
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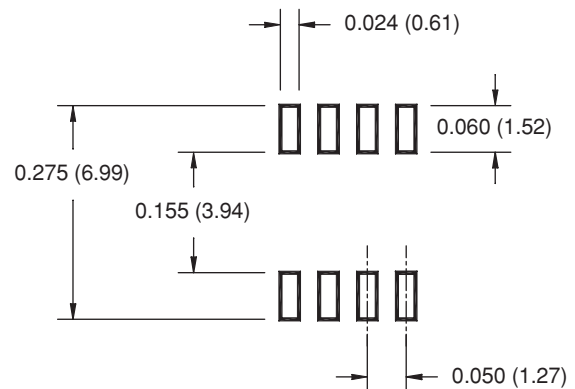
FOD270L

SOIC 8

Package Dimensions (Surface Mount)



Recommend Pad Layout



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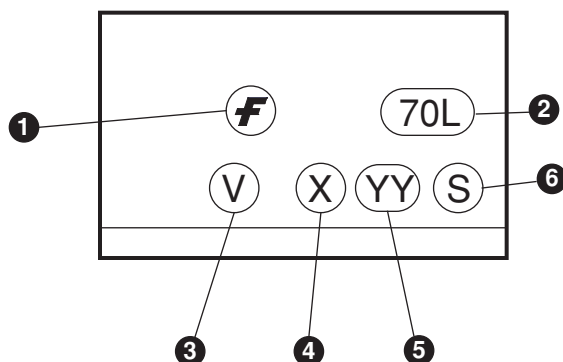
**FOD070L
FOD073L**

FOD270L

ORDERING INFORMATION

Option	Order Entry Identifier	Description
S	FOD270LS	Surface Mount Lead Bend (DIP Package Only)
SD	FOD270LSD	Surface Mount; Tape and reel (DIP Package Only) (1000 units per reel)
SV	Pending approval	Surface Mount; VDE 0884 (DIP Package Only)
SDV	Pending approval	Surface Mount; Tape and reel (DIP Package Only); VDE 0884 (1000 units per reel)
T	FOD270LT	0.4" lead spacing (DIP Package Only)
TV	Pending approval	0.4" lead spacing, VDE 0884 (DIP Package Only)
R1	FOD070LR1	Tape and reel (500 units per reel) (SOIC 8 Package only)
R1V	Pending approval	VDE, Tape and reel (500 units per reel) (SOIC 8 Package only)
R2	FOD070LR2	Tape and reel (2500 units per reel) (SOIC 8 Package only)
R2V	Pending approval	VDE 0884, Tape and reel (2500 units per reel) (SOIC 8 Package only)
V	Pending approval	VDE 0884

MARKING INFORMATION (FOD070L, FOD073L)



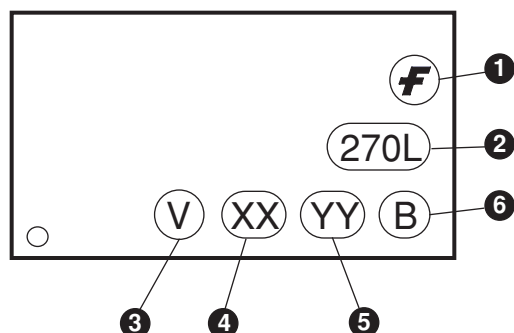
Definitions	
1	Fairchild logo
2	Device number
3	VDE mark (Note: Only appears on parts ordered with VDE option – See order entry table)
4	One digit year code, e.g., '3'
5	Two digit work week ranging from '01' to '53'
6	Assembly package code

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MARKING INFORMATION (FOD270L)



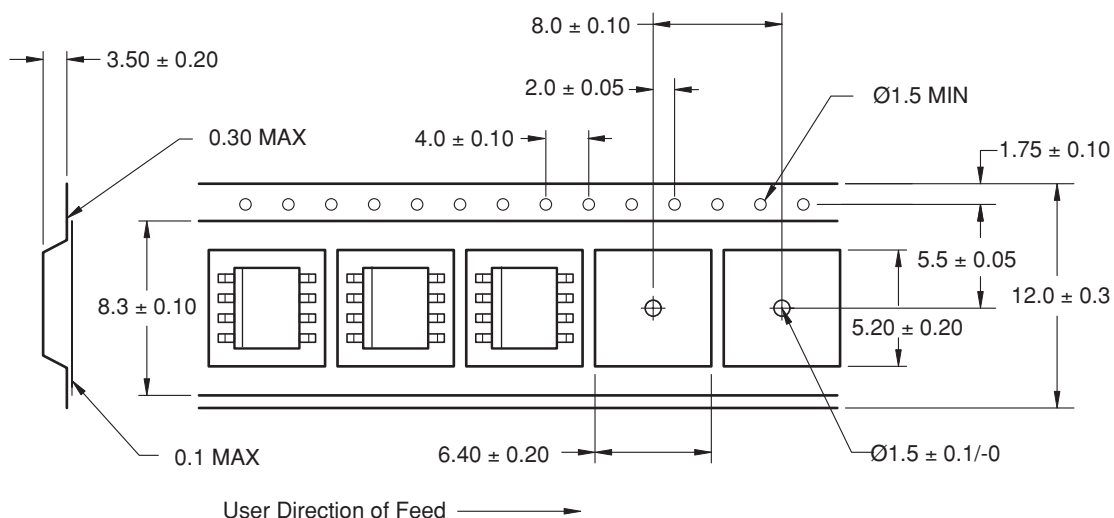
Definitions	
1	Fairchild logo
2	Device number
3	VDE mark (Note: Only appears on parts ordered with VDE option – See order entry table)
4	Two digit year code, e.g., '03'
5	Two digit work week ranging from '01' to '53'
6	Assembly package code

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Carrier Tape Specifications (FOD070L and FOD073L)

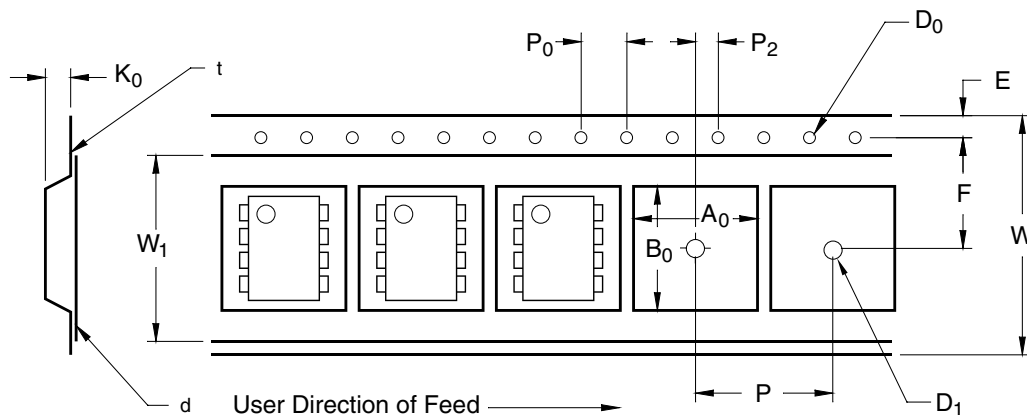


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Carrier Tape Specifications (FOD270L)



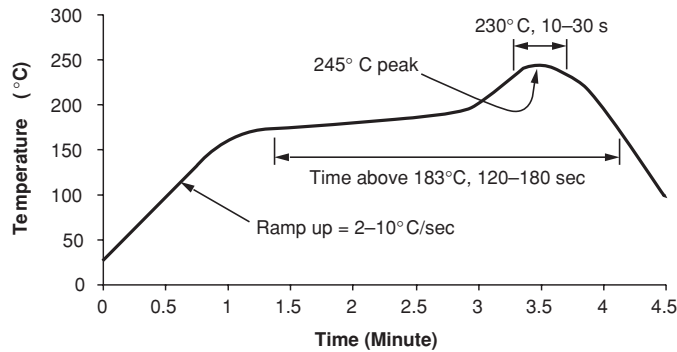
Description	Symbol	Dimension in mm
Tape Width	W	16.0 ± 0.3
Tape Thickness	t	0.30 ± 0.05
Sprocket Hole Pitch	P_0	4.0 ± 0.1
Sprocket Hole Diameter	D_0	1.55 ± 0.05
Sprocket Hole Location	E	1.75 ± 0.10
Pocket Location	F	7.5 ± 0.1
Pocket Pitch	P	12.0 ± 0.1
Pocket Dimensions	A_0	10.30 ± 0.20
	B_0	10.30 ± 0.20
	K_0	4.90 ± 0.20
Cover Tape Width	W_1	1.6 ± 0.1
Cover Tape Thickness	d	0.1 max
Max. Component Rotation or Tilt		10°
Min. Bending Radius	R	30

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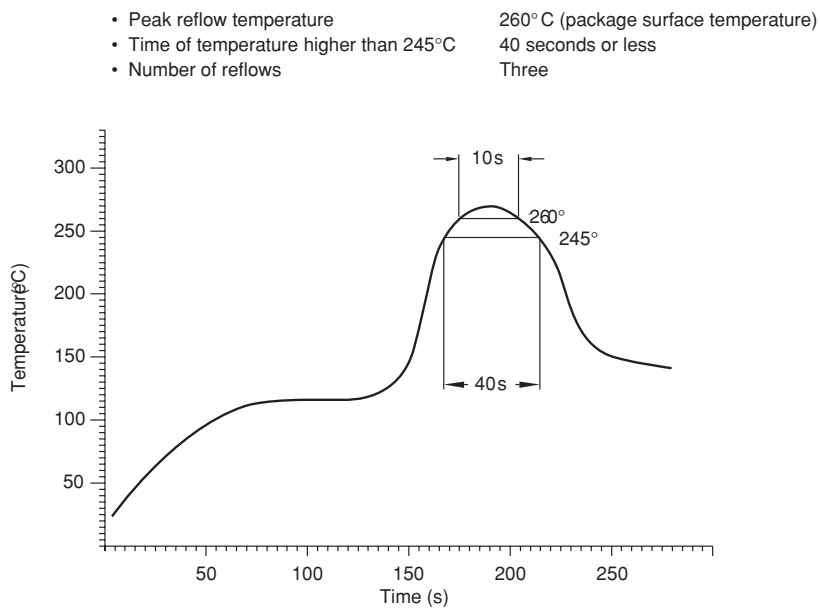
FOD270L

Reflow Profile (FOD070L and FOD073L)



- Peak reflow temperature: 245°C (package surface temperature)
- Time of temperature higher than 183°C for 120-180 seconds
- One time soldering reflow is recommended

Reflow Profile (FOD270L)



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1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.